



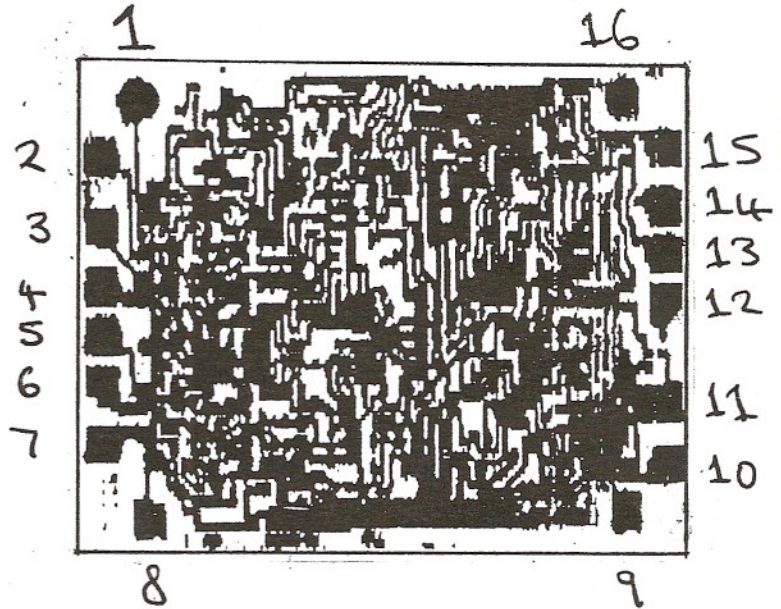
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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

<u>Pad</u>	<u>Function</u>	<u>Pad</u>	<u>Function</u>
1	IN3+	9	V-
2	IN3-	10	OUT
3	IN4+	11	V+
4	IN4-	12	COMP
5	IN1-	13	GND
6	IN1+	14	ENABLE
7	IN2-	15	D ₁
8	IN2+	16	D ₀



Topside Metal: Al
Backside: Si
Backside Potential: -
Mask Ref: -
Bond Pads: .004" min.

APPROVED BY: CD

MFG: Harris

DIE SIZE: .088" x .067"

THICKNESS: .020"

DATE: 8/5/02

P/N: HAO2405-6